



10-13-09

Docket No.: 085027-0104

**PATENT**

*Ifw*

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Application of : Customer Number: 89518  
Mou-Shiung Lin, et al. : Confirmation Number: 8665  
Application No.: 10/755,042 : Group Art Unit: 2815  
Filed: January 09, 2004 :  
For: INTEGRATED CHIP PACKAGE STRUCTURE USING SILICON SUBSTRATE AND  
METHOD OF MANUFACTURING THE SAME

**TRANSMITTAL OF POWER OF ATTORNEY**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

Transmitted herewith is a Power Of Attorney to Prosecute Applications Before the USPTO, together with a Statement Under 37 CFR 3.73(b), which revokes all previous powers of attorney given in the above-identified application and associates the application with Customer Number 89518.

Respectfully submitted,

McDERMOTT WILL & EMERY LLP

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Date: October 8, 2009

**Please recognize our Customer No. 89518  
as our correspondence address.**